

CLASS II FABRICATION NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARDS SHALL BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED IPC-D-356 NETLIST.
2. THIS BOARD SHALL BE MANUFACTURED IN ACCORDANCE WITH IPC-6012A CLASS II SPECIFICATIONS AND MEET IPC-600 CLASS II ACCEPTABILITY STANDARDS.
3. MATERIAL:

a. FR4 PER IPC 4101B/24 /26 , OR /28.

b. SIGNAL LAYERS TO BE 2 OZ. COPPER.

c. PLANE LAYERS TO BE 2 OZ. COPPER.

d. OVERALL THICKNESS TO BE 0.062" +/- 10%
4. LEGEND:

a. WHITE NON-CONDUCTIVE EPOXY INK BOTH SIDES.
5. SOLDERMASK:

a. APPLY LIQUID PHOTO-IMAGABLE (LPI) SOLDER MASK OVER BARE COPPER PER IPC-SM-840 CLASS H, COLOR GREEN, BOTH SIDES.
6. PLATING FINISH:

a. HOT AIR SOLDER LEVELING (HASL) SN63A SnPb SOLDER.

~~b. IMMERSION SILVER PLATING.~~
7. PROCESS ALLOWANCES:

a. MAXIMUM BOW AND TWIST SHALL NOT EXCEED .007" PER INCH

b. HOLE DIMENSIONS APPLY AFTER PLATING.

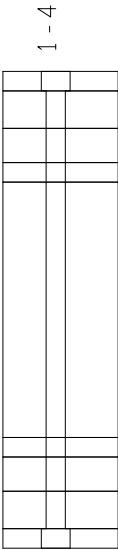
c. ALL HOLES SHALL BE LOCATED WITHIN 0.003" DIAMETER OF TRUE POSITION.

d. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003"

e. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 0.002".

f. REMOVE ALL BURRS AND BREAK SHARP EDGES 0/015" MAX.

g. CUT OUTSIDE OF 0.001" BOARD OUTLINE.



- L1: TOP CONDUCTOR - COPPER 2.7 MIL
- * DIELECTRIC - FR-4 5.1 MIL
- * DIELECTRIC - FR-4 4.7 MIL
- L2: GND CONDUCTOR - COPPER 2.7 MIL
- * DIELECTRIC - FR-4 35 MIL
- L3: PWR CONDUCTOR - COPPER 2.7 MIL
- * DIELECTRIC - FR-4 4.7 MIL
- * DIELECTRIC - FR-4 5.1 MIL
- L4: BOTTOM CONDUCTOR - COPPER 2.7 MIL

DESIGN CROSS SECTION CHART
TOTAL THICKNESS 65.4 MIL

